Product Change Notification: CAAN-25IFCC278

Date:

06-Aug-2026

Product Category:

Analog to Digital Converters, Battery Management And Fuel Gauges - Battery Chargers, Digital Potentiometers, Linear Regulators, Memory

Notification Subject:

CCB 8393 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected 11LC161, 24AA01, 24AA014, 24AA02, 24AA024, 24AA025, 24AA52, 24C01C, 24C02C, 24LC014, 24LC01B, 24LC024, 24LC025, 24LC02B, 24LCS52, MCP1725, MCP1727, MCP3423, MCP3427, MCP4232, MCP4242, MCP4252, MCP4262, MCP4632, MCP4642, MCP4652, MCP4662, MCP73833, MCP73834, MCP73837 and MCP73838 device families available in 8L DFN (2x3x0.9mm and 3x3x0.9mm) and 10L DFN (3x3x0.9mm) packages at MMT assembly site.

Affected CPNs:

CAAN-25IFCC278_Affected_CPN_08062026.pdf
CAAN-25IFCC278_Affected_CPN_08062026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected 11LC161, 24AA01, 24AA014, 24AA02, 24AA024, 24AA025, 24AA52, 24C01C, 24C02C, 24LC014, 24LC01B, 24LC024, 24LC025, 24LC02B, 24LCS52, MCP1725, MCP1727, MCP3423, MCP3427, MCP4232, MCP4242, MCP4252, MCP4262, MCP4632, MCP4642, MCP4652, MCP4662, MCP73833, MCP73834, MCP73837 and MCP73838 device families available in 8L DFN (2x3x0.9mm and 3x3x0.9mm) and 10L DFN (3x3x0.9mm) packages at MMT assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	QMI519 (PFAS-free)	QMI519 (PFAS-free)	No
Molding Compound Material	G700LTD	G700LTD	No
Lead-Frame Material	A194	A194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) as a new wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 12 October 2026 (date code: 2642)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	August 2026					>	**October 2026**				
Work Week	32	33	34	35	36		40	41	42	43	44
Qual Report Availability	X										
Final PCN Issue Date	X										
Estimated Implementation Date									X		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Note: This is a qualification by similarity (QBS) to CCB 2700, CCB 6137 and CCB 7907.

Revision History: August 06, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CAAN-25IFCC278_Qual_Report_CCB_2700.pdf
PCN_CAAN-25IFCC278_Qual_Report_CCB_6137.pdf
PCN_CAAN-25IFCC278_Qual_Report_CCB_7907.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

MCP4232T-103E/MF

MCP4232-502E/MF

MCP4242-503E/MF

MCP4252T-503E/MF

MCP4232T-502E/MF

MCP4262T-104E/MF

MCP4632T-103E/MF

MCP4652T-103E/MF

MCP4652T-502E/MF

MCP4642T-503E/MF

MCP4642T-104E/MF

MCP4662T-103E/MF

MCP4662T-502E/MF

MCP4632T-502E/MF

MCP4662T-104E/MF

MCP4652T-503E/MF

MCP4652T-104E/MF

MCP4642T-502E/MF

MCP4632T-503E/MF

MCP4632T-104E/MF

MCP4642T-103E/MF

MCP4662T-503E/MF

MCP73833-96I/MF

MCP73833T-96I/MF

MCP73834-YAI/MF

MCP73833-B6I/MF

MCP73833-6SI/MF

MCP73833-CNI/MF

MCP73834-B6I/MF

MCP73833-NVI/MF

MCP73833-GPI/MF

MCP73833-G8I/MF

MCP73834-NVI/MF

MCP73834-GPI/MF

MCP73833T-CNI/MF

MCP73834T-FCI/MF

MCP73834T-YAI/MF

MCP73834T-NVI/MF

MCP73833-AMI/MF

MCP73833T-DZI/MF

MCP73834T-G8I/MF

MCP73833T-YAI/MF

MCP73833-HAI/MF

MCP73833T-HAI/MF

MCP73833-DZI/MF

MCP73837-FCI/MF

MCP73837-NVI/MF

MCP73837-FJI/MF

MCP73838T-FCI/MF

MCP73838T-NVI/MF

MCP73838T-FJI/MF

MCP73837T-NVI/MF

MCP73837T-FJI/MF

MCP73837T-FCI/MF

MCP73838-FJI/MF

MCP73838-FCI/MF

MCP73838-NVI/MF

MCP3423T-E/MF

MCP3423-E/MF

MCP3427-E/MF

MCP3427T-E/MF

11LC161T-E/MC

24LC01BT-I/MC

24LC01BT-E/MC

MCP73833-FCI/MF

MCP73833-YAI/MF

MCP73834-6SI/MF

MCP73834-G8I/MF

MCP73833-BZI/MF

MCP73834-FCI/MF

MCP73834-CNI/MF

MCP73834T-B6I/MF

MCP73834T-6SI/MF

MCP73834T-GPI/MF

MCP73833T-NVI/MF

MCP73833T-GPI/MF

MCP73833T-G8I/MF

MCP73833T-FCI/MF

MCP73834T-CNI/MF

MCP73833T-BZI/MF

MCP73833T-B6I/MF

MCP73833T-AMI/MF

MCP73833T-6SI/MF

24AA01T-I/MC

24LC01B-E/MC

24LC02BT-I/MC

24LC02BT-E/MC

24AA02T-I/MC

24AA52T-I/MC

24LCS52T-I/MC

24AA52-I/MC

24LCS52-I/MC

24LC024T-I/MC

24AA025T-I/MC

24LC024-E/MC

24LC024T-E/MC

24AA024T-I/MC

24LC025T-I/MC

24LC025T-E/MC

24AA025-I/MC

24LC025-I/MC

24AA024-I/MC

24LC024-I/MC

24LC025-E/MC

MCP4242-502E/MF

MCP4232-503E/MF

MCP4252-104E/MF

MCP4262-103E/MF

MCP4232-103E/MF

MCP4242-104E/MF

MCP4232-104E/MF

MCP4252T-104E/MF

MCP4252T-103E/MF

MCP4252T-502E/MF

MCP4262T-503E/MF

MCP4242T-104E/MF

MCP4242T-103E/MF

MCP4242T-502E/MF

MCP4232T-503E/MF

MCP4232T-104E/MF

24LC014-I/MC

24AA014-I/MC

24LC014T-E/MC

24AA014T-I/MC

24LC014T-I/MC

24LC014-E/MC

24C02CT-E/MC

24C02CT-I/MC

24C02C-E/MC

24C01CT-I/MC

24C01CT-E/MC

24C01C-I/MC

24C01C-E/MC

MCP1727-5002E/MF

MCP1727-3302E/MF

MCP1727-ADJE/MF

MCP1727-3002E/MF

MCP1727-1202E/MF

MCP1727T-2502E/MF

MCP1727T-3002E/MF

MCP1727-0802E/MF

MCP1727T-3302E/MF

MCP1727T-1802E/MF

MCP1727T-0802E/MF

MCP1727T-1202E/MF

MCP1727-2502E/MF

MCP1727T-5002E/MF

MCP1727-1802E/MF

MCP1727T-ADJE/MF

MCP1725T-3002E/MC

MCP1725T-ADJE/MC

MCP1725T-5002E/MC

MCP1725T-1802E/MC

MCP1725-1802E/MC

MCP1725T-3302E/MC

MCP1725-0802E/MC

MCP1725-1202E/MC

MCP1725-3002E/MC

MCP1725-2502E/MC

MCP1725-3302E/MC

MCP1725T-1202E/MC

MCP1725T-0802E/MC

MCP1725T-2502E/MC

MCP1725-ADJE/MC

MCP4252-503E/MF

MCP4252-103E/MF

MCP4262-104E/MF

MCP4262T-103E/MF

MCP4262T-502E/MF

MCP4242T-503E/MF

MCP4252-502E/MF

MCP4262-503E/MF

MCP4262-502E/MF

MCP4242-103E/MF

Qualification Report Summary

RELIABILITY LABORATORY

PCN #: CAAN-25IFCC278

Date:

October 18, 2016

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected 11LC161, 24AA01, 24AA014, 24AA02, 24AA024, 24AA025, 24AA52, 24C01C, 24C02C, 24LC014, 24LC01B, 24LC024, 24LC025, 24LC02B, 24LCS52, MCP1725, MCP1727, MCP3423, MCP3427, MCP4232, MCP4242, MCP4252, MCP4262, MCP4632, MCP4642, MCP4652, MCP4662, MCP73833, MCP73834, MCP73837 and MCP73838 device families available in 8L DFN (2x3x0.9mm and 3x3x0.9mm) and 10L DFN (3x3x0.9mm) packages at MMT assembly site.

PACKAGE QUALIFICATION REPORT

Purpose: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected 11LC161, 24AA01, 24AA014, 24AA02, 24AA024, 24AA025, 24AA52, 24C01C, 24C02C, 24LC014, 24LC01B, 24LC024, 24LC025, 24LC02B, 24LCS52, MCP1725, MCP1727, MCP3423, MCP3427, MCP4232, MCP4242, MCP4252, MCP4262, MCP4632, MCP4642, MCP4652, MCP4662, MCP73833, MCP73834, MCP73837 and MCP73838 device families available in 8L DFN (2x3x0.9mm and 3x3x0.9mm) and 10L DFN (3x3x0.9mm) packages at MMT assembly site.

CN:	ES074394-16085
QUAL ID:	Q16154
QUAL ID Rev.:	A
MP CODE:	DFAX17C2XA00
Part No.:	24LCS52-I/SN
Bonding No.:	BDM-001092 Rev. A
CCB No.:	2700 and 8393

Lead Frame

Paddle Size:	90 x 90 mils
Material:	CDA194
DAP Surface Prep:	Bare Cu
Process:	Stamped
Lead Lock:	No
Part Number:	10100812
Lead Plating:	Matte Tin
Treatment:	BOT

Bond Wire

Wire:	CuPdAu wire

Die Attach Material

Epoxy:	8390A

Mold Compound

Mold Compound:	G600V

Package

Type:	8L SOIC
Package Size:	150 mils

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-172000926.000	GRSM416340236.000	1632C0K
MMT-172100581.000	GRSM416340236.000	1633K53
MMT-172100625.000	GRSM416340236.000	1633K88

Result: **Pass**

Conclusion:

8L SOIC (.150”) assembled by MMT pass reliability test per QCI-39000.This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020D standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 1)	85°C/ 85%RH Moisture Soak 168 hrs. **System:** TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max **System:** Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020D)	IPC/JEDEC J-STD-020D	135	0/135	Pass	
Precondition Prior Perform Reliability Tests (At MSL Level 1)	**Electrical Test :**+25°C and 85°C **System:** NEXTEST_PT	JESD22-A113	693(0)	693		Good Devices
	Bake 150°C, 24 hrs **System:** CHINEE			693		
	85°C/85%RH Moisture Soak 168 hrs. **System:** TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max **System:** Vitronics Soltec MR1243			693		
	Electrical Test :+25°C and 85°C **System:** NEXTEST_PT			0/693	Pass	
Temp Cycle	**Stress Condition:** (Standard) 65°C to +150°C, 500 Cycles **System :** TABAI ESPEC TSA-70H	JESD22-A104	231			Parts had been pre-conditioned at 260°C
	Electrical Test: + 85°C **System:** J750		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (> 2.5 grams)		15 (0)	0/15	Pass	
	Bond Strength: Bond Shear (>15.00 grams)		15 (0)	0/15	Pass	
UNBIASED-HAST	**Stress Condition:** (Standard) +130°C/85%RH, 96 hrs. **System:** HAST 6000X	JESD22-A118	231			Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C **System:** J750		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
HAST	**Stress Condition:** (Standard) +130°C/85%RH, 96 hrs. Bias Volt: 5.0 Volts **System:** HAST 6000X	JESD22-A110	231			Parts had been pre-conditioned at 260°C
	Electrical Test:+25°C and 125°C **System:** J750		231(0)	0/231	Pass	77 units / lot
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 504 hrs **System:** SHEL LAB **Electrical Test :**+25°C and 85°C **System:** NEXTEST_PT	JESD22-A103	45(0)	0/45	Pass	45 units
Bond Strength Data Assembly	Wire Pull (> 2.5 grams)	M2011	30 (0)	0/30	Pass	
	Bond Shear (>15.00 grams)	JESD22-B116	30 (0)	0/30	Pass	

Qualification Report Summary

RELIABILITY LABORATORY

PCN #: CAAN-25IFCC278

Date:

September 25, 2023

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected 11LC161, 24AA01, 24AA014, 24AA02, 24AA024, 24AA025, 24AA52, 24C01C, 24C02C, 24LC014, 24LC01B, 24LC024, 24LC025, 24LC02B, 24LCS52, MCP1725, MCP1727, MCP3423, MCP3427, MCP4232, MCP4242, MCP4252, MCP4262, MCP4632, MCP4642, MCP4652, MCP4662, MCP73833, MCP73834, MCP73837 and MCP73838 device families available in 8L DFN (2x3x0.9mm and 3x3x0.9mm) and 10L DFN (3x3x0.9mm) packages at MMT assembly site. This is a Q100 Grade 1 qualification.

PACKAGE QUALIFICATION REPORT

Purpose: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected 11LC161, 24AA01, 24AA014, 24AA02, 24AA024, 24AA025, 24AA52, 24C01C, 24C02C, 24LC014, 24LC01B, 24LC024, 24LC025, 24LC02B, 24LCS52, MCP1725, MCP1727, MCP3423, MCP3427, MCP4232, MCP4242, MCP4252, MCP4262, MCP4632, MCP4642, MCP4652, MCP4662, MCP73833, MCP73834, MCP73837 and MCP73838 device families available in 8L DFN (2x3x0.9mm and 3x3x0.9mm) and 10L DFN (3x3x0.9mm) packages at MMT assembly site. This is a Q100 Grade 1 qualification.

CN:	E000170475
QUAL ID:	R2300764
QUAL ID Rev.:	A
MP CODE:	D5AL2YE2XR05
Part No.:	MCP4262T-502E/MF
Bonding No.:	BD-001162 Rev. 02
CCB No.:	6137 and 8393

Lead Frame

Paddle Size:	71 x 102 mils
Material:	A194
DAP Surface Prep:	AG selective
Process:	Etched
Lead Lock:	Yes
Part Number:	10101005
Lead Plating:	Matte Tin

Bond Wire

Wire:	Au wire

Die Attach Material

Epoxy:	8600

Mold Compound

Mold Compound:	G700LTD

Package

Type:	10L DFN
Package Size:	3 x 3 x 0.9 mm

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-240301934.000	TMPE223454608.400	2316UAT
MMT-240302068.000	TMPE223454608.400	231610W
MMT-240302069.000	TMPE223454608.400	2316112

Result: **Pass**

Conclusion:

10L DFN (3x3x0.9 mm) assembled by MMT pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 1)	**Electrical Test:** +25°C, 85°C and 125°C **System:** J750	JESD22-A113	693(0)	0/693		Good Devices
	Bake 150°C, 24 hrs. **System:** CHINEE	JIP/IPC/JEDEC J-STD-020E	693			
	85°C/85%RH Moisture Soak 168 hrs. **System:** TABAI ESPEC Model PR-3SPH		693			
	3x Convection-Reflow 265°C max **System:** Vitronics Soltec MR1243		693			
	Electrical Test: +25°C, 85°C and 125°C **System:** J750		693(0)	0/693	Pass	
Temp Cycle	**Stress Condition:** -65°C to +150°C, 500 Cycles **System:** TABAI ESPEC TSA-70H	JESD22-A104	231(0)	0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: +85°C and 125°C **System:** J750		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>2.50 grams)		15(0)	0/15	Pass	
UNBIASED-HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. **System:** HAST 6000X	JESD22-A118	231(0)	0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C **System:** J750		231(0)	0/231	Pass	77 units / lot
HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. Bias Volt: 5.5 Volts **System:** HAST 6000X	JESD22-A110	231(0)	0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C, 85°C and 125°C **System:** J750		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 500 hrs. **System:** SHEL LAB	JESD22-A103	45(0)	0/45		45 units
	Electrical Test: +25°C, 85°C and 125°C **System:** J750			0/45	Pass	
Solderability Temp 215°C	**Steam Aging:** Temp 93°C,8Hrs **System:** SAS-3000	J-STD-002	22(0)	0/22		
	Solder Dipping: Solder Temp.215°C **Solder material:** SnPb Sn63, Pb37 **System:** ERSA RA 2200D			0/22		
	Visual Inspection: External Visual Inspection			0/22	Pass	
Solderability Temp 245°C	**Steam Aging:** Temp 93°C,8Hrs **System:** SAS-3000	J-STD-002	22(0)	0/22		
	Solder Dipping: Solder Temp.245°C **Solder material:**Pb Free Sn 95.5Ag3.9 Cu0.6 **System:** ERSA RA 2200D			0/22		
	Visual Inspection: External Visual Inspection			0/22	Pass	
Physical Dimensions	Physical Dimension, 10 units / 1 lot	JESD22-B100 /B108	30(0)	0/30	Pass	
Bond Strength Data Assembly	Wire Pull (>2.50 grams)	Mil. Std. 883-2011	30(0)	0/30	Pass	
	Bond Shear (>15.00 grams)	CDF-AEC-Q1 00-001	30(0)	0/30	Pass	

Qualification Report Summary

RELIABILITY LABORATORY

PCN #: CAAN-25IFCC278

Date

April 22, 2026

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected 11LC161, 24AA01, 24AA014, 24AA02, 24AA024, 24AA025, 24AA52, 24C01C, 24C02C, 24LC014, 24LC01B, 24LC024, 24LC025, 24LC02B, 24LCS52, MCP1725, MCP1727, MCP3423, MCP3427, MCP4232, MCP4242, MCP4252, MCP4262, MCP4632, MCP4642, MCP4652, MCP4662, MCP73833, MCP73834, MCP73837 and MCP73838 device families available in 8L DFN (2x3x0.9mm and 3x3x0.9mm) and 10L DFN (3x3x0.9mm) packages at MMT assembly site. This is a Q100 Grade 1 qualification. .

PACKAGE QUALIFICATION REPORT

Purpose: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected 11LC161, 24AA01, 24AA014, 24AA02, 24AA024, 24AA025, 24AA52, 24C01C, 24C02C, 24LC014, 24LC01B, 24LC024, 24LC025, 24LC02B, 24LCS52, MCP1725, MCP1727, MCP3423, MCP3427, MCP4232, MCP4242, MCP4252, MCP4262, MCP4632, MCP4642, MCP4652, MCP4662, MCP73833, MCP73834, MCP73837 and MCP73838 device families available in 8L DFN (2x3x0.9mm and 3x3x0.9mm) and 10L DFN (3x3x0.9mm) packages at MMT assembly site. This is a Q100 Grade 1 qualification.

QUAL ID: R2501550
QUAL ID Rev.: A
MP CODE: 669024A6XS00
Part No.: 25CSM01-E/MF
Bonding No.: BD-003900-01
CCB No.: 7907 and 8393

Lead Frame

Paddle Size: 173 x 173 mils
Material: A194
DAP Surface Prep: Bare Cu
Process: Etched
Lead Lock: Locking hole
Part Number: 10100879
Lead Plating: Matte tin
Treatment: Roughened

Bond Wire

Wire: CuPdAu

Die Attach Material

Epoxy: QMI519
Conductive: Yes

Mold Compound

Mold Compound: G700LTD

Package

Type: 8L DFN-S
Package Size: 6x5x0.9 mm

Manufacturing Information

Assembly Lot No.
MMT-263301084.000
MMT-263301129.000
MMT-263301130.000

Result: **Pass**

Conclusion:
Qualification of 66902 mask / 25CSM01-E/MF product / CuPdAu wire in 8L DFN-S 6x5x0.9 mm package at MMT site is qualified for MSL1 at 260ºC as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Precondition (Moisture Soak)	**MSL1:** 150°C 24 hours Bake, 168 hours Moisture Soak at 85°C/85%RH, 3x Reflow at 260°C	JESD22-A113 , JEDEC J-STD-020	693(0)	0/693	Pass	Electrical Test: 25°C, 85°C, and 125°C. Tester: NEXTEST_PT
High Temp Storage	175°C / 500 hours	JESD22-A103	135(0)	0/135	Pass	Electrical Test: 25°C, 85°C, and 125°C. Tester: NEXTEST_PT
High Temp Storage	175°C / 1000 hours	JESD22-A103	135(0)	0/135	Pass	Electrical Test: 25°C, 85°C, and 125°C. Tester: NEXTEST_PT
Temperature Cycling	-55°C / +150°C Air to Air / 1000 Cycles	JESD22-A104	231(0)	0/231	Pass	Electrical Test: 25°C, 85°C, and 125°C. Tester: NEXTEST_PT
	-55°C / +150°C Air to Air / 1000 Cycles		9(0)	0/9	Pass	Wire Bond Pull
	-55°C / +150°C Air to Air / 1000 Cycles		9(0)	0/9	Pass	Wire Bond Shear
Temperature Cycling	-55°C / +150°C Air to Air / 2000 Cycles	JESD22-A104	231(0)	0/231	Pass	Electrical Test: 25°C, 85°C, and 125°C. Tester: NEXTEST_PT
	-55°C / +150°C Air to Air / 2000 Cycles		9(0)	0/9	Pass	Wire Bond Pull
	-55°C / +150°C Air to Air / 2000 Cycles		9(0)	0/9	Pass	Wire Bond Shear
Biased HAST	+130°C / 85%RH / 96 hours / Bias Voltage: 5.6V	JESD22-A110	231(0)	0/231	Pass	Electrical Test: 25°C, 85°C, and 125°C. Tester: NEXTEST_PT
	+130°C / 85%RH / 96 hours / Bias Voltage: 5.6V		9(0)	0/9	Pass	Wire Bond Pull
	+130°C / 85%RH / 96 hours / Bias Voltage: 5.6V		9(0)	0/9	Pass	Wire Bond Shear

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Biased HAST	+130°C / 85%RH / 192 hours / Bias Voltage: 5.6V	JESD22-A110	231(0)	0/231	Pass	Electrical Test: 25°C, 85°C, and 125°C. Tester: NEXTEST_PT
	+130°C / 85%RH / 192 hours / Bias Voltage: 5.6V		9(0)	0/9	Pass	Wire Bond Pull
	+130°C / 85%RH / 192 hours / Bias Voltage: 5.6V		9(0)	0/9	Pass	Wire Bond Shear
Unbiased HAST	+130°C / 85%RH / 96 hours	JESD22-A118	231(0)	0/231	Pass	Electrical Test: 25°C. Tester: NEXTEST_PT
Solderability (0 Hr) Method 1: Dip and Look	Pb-free 8 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage	J-STD-002 / JESD22B-102	22(0)	0/22	Pass	
Physical Dimension (0Hr)	Within package diagram dimension	JESD22 B100 and B108	30(0)	0/30	Pass	
Wire Pull	Bond Strength Data Assembly	Mil. Std. 883-2011	5(0)	0/5	Pass	
Bond Shear	Bond Strength Data Assembly	CDF-AEC-Q1 00-001	5(0)	0/5	Pass	